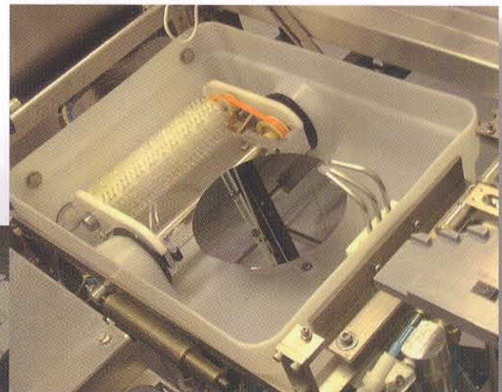
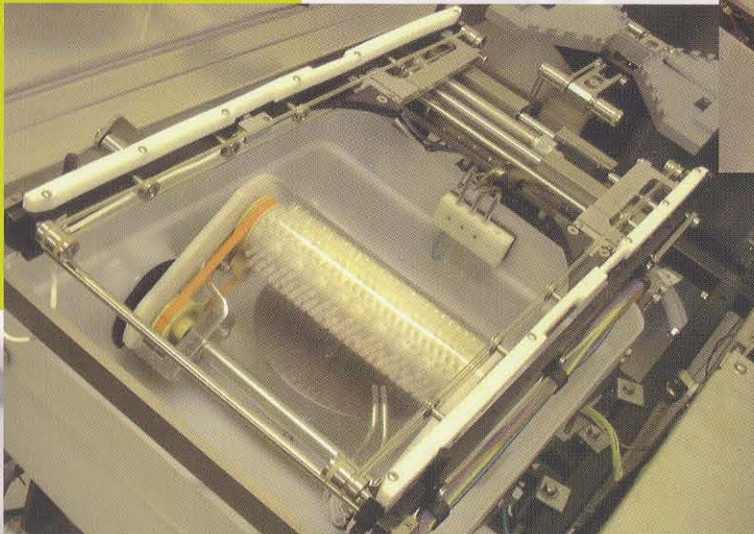
SCRUBBER (WAFER CLEANER)

The SVG* 86 and 88 series SSC (single sided cleaner) scrubbers clean 2" to 150mm wafers with a brush scrub and/or high pressure metal lift-off. Both series of scrubber systems have flexible process options for ease of use and improved process capability.

Mission Technology Inc. provides remanufacturing and upgrades of both series of single sided cleaning systems. In addition to restoring the interior and exterior aspects of the system, we also enhance the system with upgraded parts and/or modules, which have been tested rigorously in the field. Several example of these components are listed below:

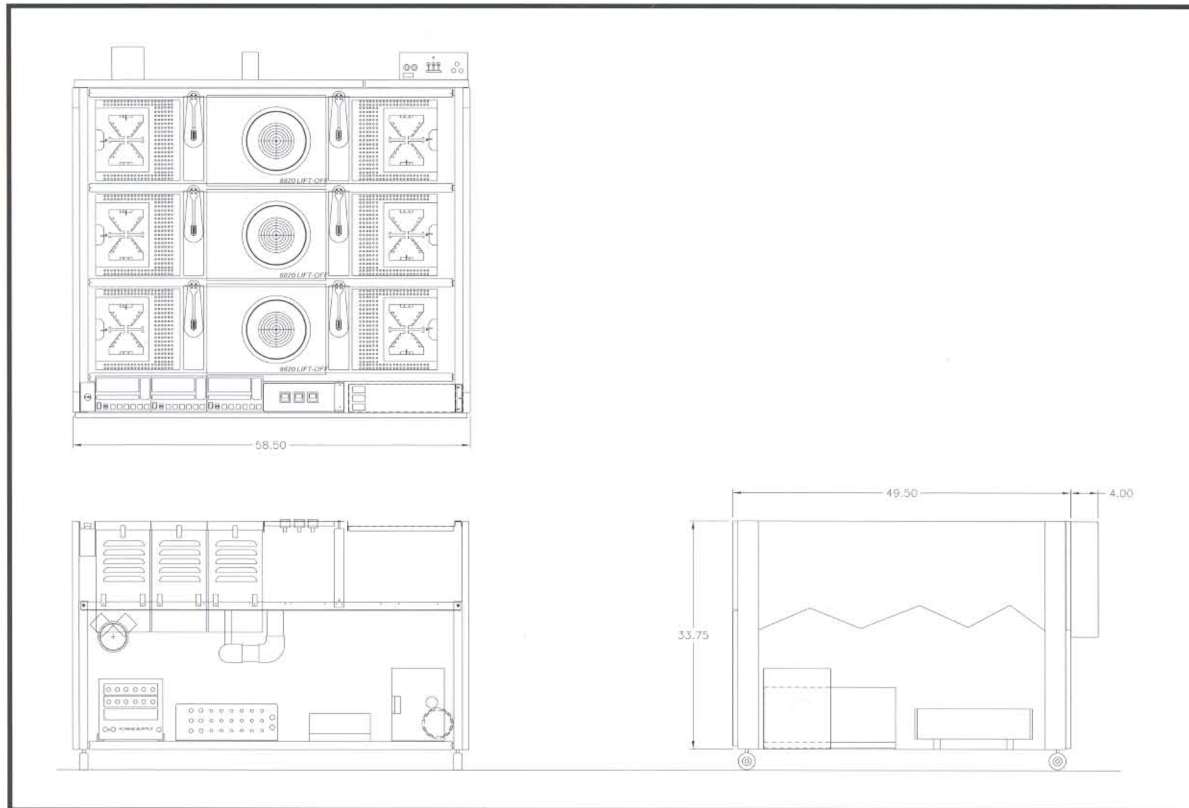




IMPROVED AIR RINGS keep the wafer and the chuck completely dry during processing.

ADJUSTABLE HIGH PRESSURE NOZZLE provides better coverage of the full wafer diameter during each cleaning cycle, and reduces static build-up.

*SVG IS A TRADE MARK OF SILICON VALLEY GROUP



CONFIGURATION DRAWING SHOWN IN 88XX SERIES

Category	Feature	Specification	Facility Requirements	
System Basic	Wafer Size	3"-6" Wafers (100mm – 150mm)	Power	208 VAC, 3 Phase, 15A
	User Interface / Controller	Card Cage		(Different voltage/Phase
Vapor Prime	Temperature Range	50 - 250°C ±0.5°C (50-150°C), ±0.5% (151-250°C)		combination possible)
Chill Plate	Temperature Range	18.0 - 30°C ±0.1°C with chiller (idle at ambient)		
HPO	Temperature Range	50 - 250°C ±0.5°C (50-150°C), ±0.5% (151-250°C)	N_2	80 PSI
Scrubber	Maximum Spin Speed	6000 rpm (with 6" wf), 8500 rpm (without wf)	CDA	80 PSI
	Spin Speed Accuracy	≤ 2 rpm	Exhaust	2.5 inch H_2O
	Acceleration Range	0-50000 rpm / sec.	Vacuum	30 inch Hg
	Chuck Temp. Uniformity	≤ 0.2 °C across Spin Chuck	DI Water	25 PSI
	Brush Speed	100 – 600 rpm in 1 rpm increment	PCW	17°C (± 2°C)
	Brush Force	Adjustable from 0 to 2 lbs		
	High Pressure Arm Sweep	Programmable from 25 to 99 cycles per minute		
	Sweep Nozzle Pressure	Low Pres.: 400 – 1400 psi, High Pres.: 1400 – 5000 psi		
	Wafer Transfer	ATS Transfer Arm		
	Particle Level	≤ 100 Particles @ 0.2 μm, With Prime Test Wafers		
Reliability	MTBF	≥200 hours		
	MTBA	≥50 hours		
	MWBF	≥10,000 wafers		
	MWBA	≥2,000 wafers		
	Uptime	≥95%		
	Wafer Breakage	≤1 in 10,000 wafers		
Safety	Teflon Wiring	Standard		
	Solvent Plumbing	Teflon or S.S.		
	Spill Container in Cabinet	Custom		
	Exhausted Cabinet	Option		

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